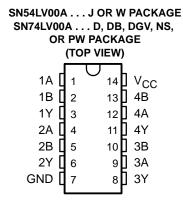
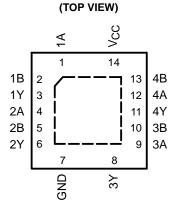
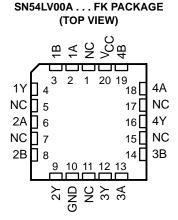
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- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 6.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)





SN74LV00A . . . RGY PACKAGE



NC - No internal connection

description/ordering information

These quadruple 2-input positive-NAND gates are designed for 2-V to 5.5-V V_{CC} operation.

The 'LV00A devices perform the Boolean function $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Reel of 1000	SN74LV00ARGYR	LV00A
1	SOIC – D	Tube of 50	SN74LV00AD	LV00A
	3010 - 0	Reel of 2500	SN74LV00ADR	LVUUA
	SOP - NS	Reel of 2000	SN74LV00ANSR	74LV00A
–40°C to 85°C	SSOP – DB	Reel of 2000	SN74LV00ADBR	LV00A
		Tube of 90	SN74LV00APW	
	TSSOP – PW	Reel of 2000	SN74LV00APWR	LV00A
		Reel of 250	SN74LV00APWT	
	TVSOP - DGV	Reel of 2000	SN74LV00ADGVR	LV00A
	CDIP – J	Tube of 25	SNJ54LV00AJ	SNJ54LV00AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV00AW	SNJ54LV00AW
	LCCC - FK	Tube of 55	SNJ54LV00AFK	SNJ54LV00AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design quidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Н	L
L	X	Н
Х	L	Н

logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Output voltage range, VO (see Notes 1 and 2)	
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	
Continuous output current, I_O ($V_O = 0$ to V_{CC})	
Continuous current through V _{CC} or GND	
Package thermal impedance, θ_{JA} (see Note 3): D package	86°C/W
(see Note 3): DB package	
(see Note 3): DGV package	127°C/W
(see Note 3): NS package	76°C/W
(see Note 3): PW package	113°C/W
(see Note 4): RGY package	47°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.
- 4. The package thermal impedance is calculated in accordance with JESD 51-5.



recommended operating conditions (see Note 5)

			SN54	SN54LV00A		_V00A	UNIT	
			MIN	MAX	MIN	MAX	UNII	
Vcc	Supply voltage		2	5.5	2	5.5	V	
		V _{CC} = 2 V	1.5		1.5			
VIH	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} × 0.7		$V_{CC} \times 0.7$		V	
۷IH	High-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	V _{CC} × 0.7		$V_{CC} \times 0.7$		V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$			
		V _{CC} = 2 V		0.5		0.5		
VII	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	V	
V IL	Low level input voitage	$V_{CC} = 3 V \text{ to } 3.6 V$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	v	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$		
٧ _I	Input voltage		0	5.5	0	5.5	V	
٧o	Output voltage		0 ,	Vcc	0	VCC	V	
		V _{CC} = 2 V	S	-50		-50	μΑ	
lou	High-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	90	-2		-2		
ЮН	riigii-ievei output current	$V_{CC} = 3 V \text{ to } 3.6 V$	d Q	-6		-6	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		-12		
		V _{CC} = 2 V		50		50	μΑ	
loL	Low-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2		
IOL	Low-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		6		6	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12		12		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		200		
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 3 V \text{ to } 3.6 V$		100		100	ns/V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20		20		
T_A	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		SN5	4LV00A		SN7	UNIT			
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	TYP	MAX	UNII	
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			V _{CC} -0.1				
\/a	$I_{OH} = -2 \text{ mA}$	2.3 V	2			2			V	
Voн	$I_{OH} = -6 \text{ mA}$	3 V	2.48			2.48			V	
	I _{OH} = -12 mA	4.5 V	3.8	3		3.8				
	I _{OL} = 50 μA	2 V to 5.5 V		Ŋ	0.1			0.1		
\/a-	I _{OL} = 2 mA	2.3 V		25	0.4			0.4	0.4 V	
VOL	I _{OL} = 6 mA	3 V	ć		0.44			0.44	V	
	I _{OL} = 12 mA	4.5 V	200		0.55			0.55		
lį	V _I = 5.5 V or GND	0 to 5.5 V	0		±1			±1	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	Q.		20			20	μΑ	
l _{off}	V_I or $V_O = 0$ to 5.5 V	0			5			5	μΑ	
C.	V: - Voc or GND	3.3 V		3.3			3.3		n.E	
C _i	$V_I = V_{CC}$ or GND	5 V		3.3			3.3		pF	

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	PARAMETER FROM TO		LOAD	T,	4 = 25°C	;	SN54LV00	PΑ	SN74L	V00A	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN M	АХ	MIN	MAX	UNII
t	Δ.	V	C _L = 15 pF		7.1*	12.9*	9*11	16*	1	15	no
^t pd	^	· ·	C _L = 50 pF		9.6	16.6	29	21	1	20	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER FROM		то	LOAD	T _A = 25°C		SN54LV00A	SN74L	SN74LV00A		
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
tout	۸		C _L = 15 pF		5*	7.9*	1* 10.5	1	9.5	ne
^t pd	A	ī	C _L = 50 pF		6.9	11.4	1 14	1	13	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	4 = 25°C	;	SN54LV00A		SN74L	V00A	LINIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN MA	Х	MIN	MAX	UNIT
foot	۸	^	C _L = 15 pF		3.6*	5.5*	1* 7.	5*	1	6.5	ns
^t pd	A	'	C _L = 50 pF		4.9	7.5	1 9	.5	1	8.5	118

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 6)

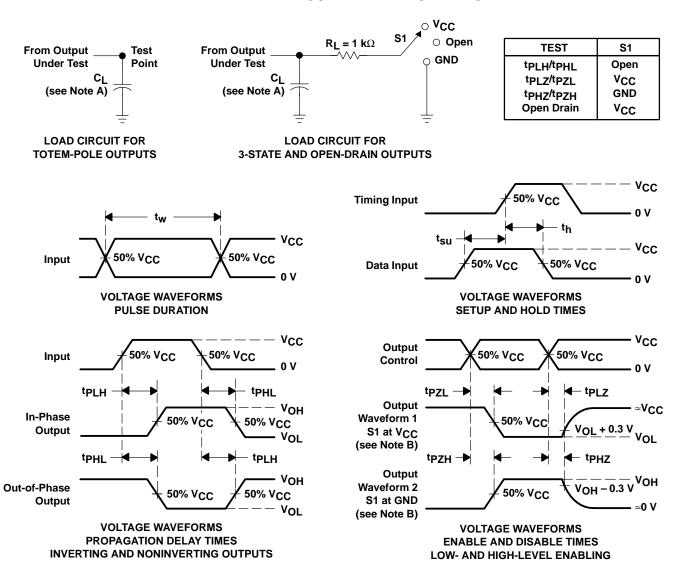
	PARAMETER			SN74LV00A			
	PARAMETER		TYP	MAX	UNIT		
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.2	0.8	V		
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.1	-0.8	V		
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		3.1		V		
VIH(D)	High-level dynamic input voltage	2.31			V		
V _{IL(D)}	Low-level dynamic input voltage			0.99	V		

NOTE 6: Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

	PARAMETER	TEST CO	۷ _{CC}	TYP	UNIT	
C	Power dissipation capacitance	$C_1 = 50 pF$	f = 10 MHz	3.3 V	9.5	pF
Cpd	Tower dissipation capacitance	CL = 50 pr,	1 = 10 1011 12	5 V	11	ρı

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 3 ns, $t_f \leq$ 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. t_{PHL} and t_{PLH} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE

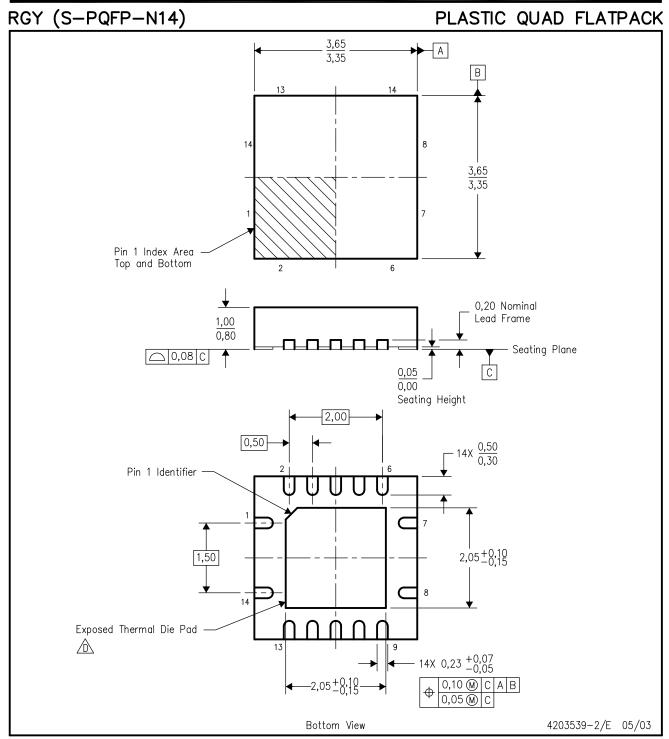


NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



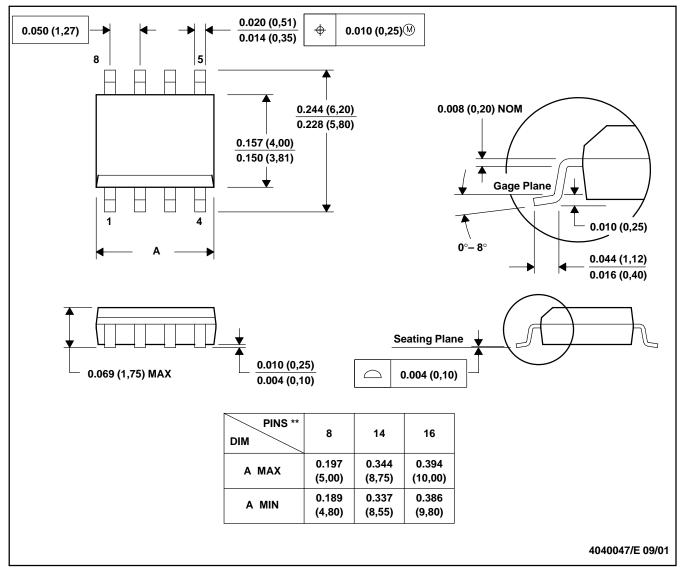
- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
 - E. Package complies to JEDEC MO-241 variation BA.



D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

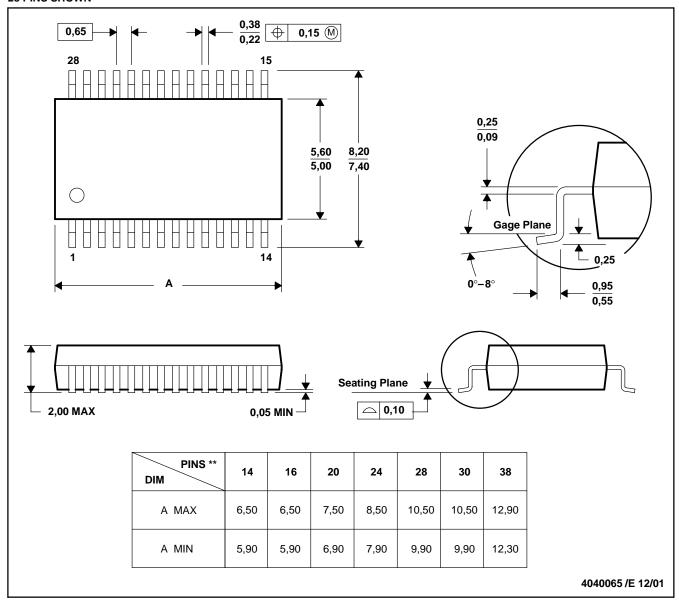
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

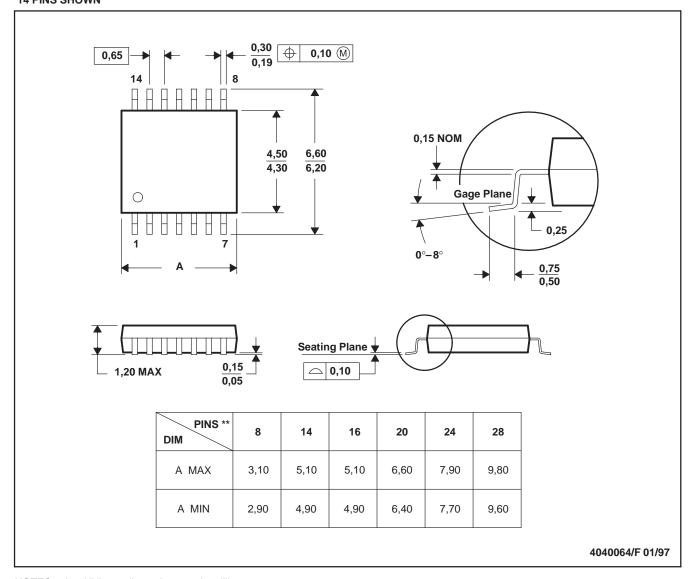
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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